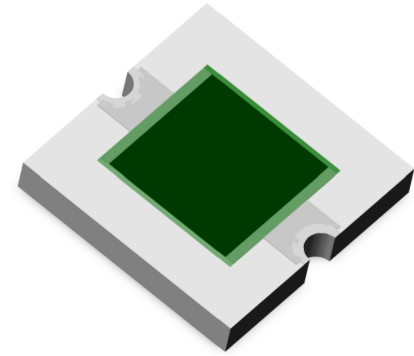


RYC2525ZZ-XXXXWN-99 Features:

- Wraparound w/ Isolated Center Pad Configuration •
- Solder, Wire-bond, or Epoxy Attachment Available
- Solder or Epoxy Mount Backplane
- Customer Defined Testing Available
- RoHS Compliant Available
- Tape & Reel or Waffle Pack Available (Standard is bulk)
- 1, 2, or 5% Resistor Tolerance Available
- Non-Magnetic Available

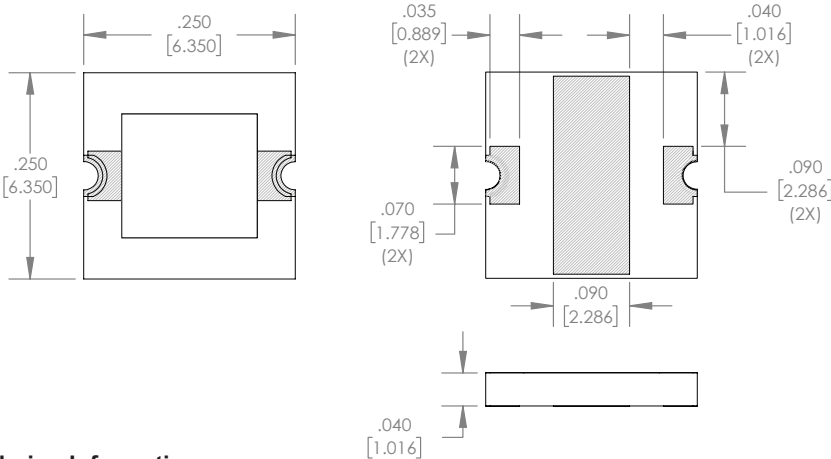


RYC2525ZZ-XXXXWN-99 Parameters:

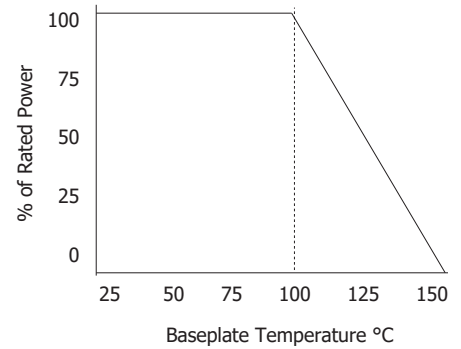
Resistance Range:	0.5Ω - 1MΩ
Rated Power:	100W*
Construction:	Thick Film on BeO
Operating Temperature:	-55 to +150°C

* Rating based on ≤100°C constant baseplate temperature

RYC2525ZZ-XXXXWN-99 Dimensions:



RYC2525ZZ-XXXXWN-99 Power Derating Curve



Dimensions in inches [mm]
Tolerance is ± 0.010 [0.254]
unless otherwise stated

Ordering Information:

RYC	2525	ZZ	-	XXXX	W	N	-	99	UU
Prefix for Wraparound Resistor w/ Isolated Backpad	Size	Value Code Examples		Tolerance	Normal Inspection	Substrate		Packaging	
	2525	10R0 - 10Ω 1000 - 100Ω 1001 - 1KΩ		F - 1% G - 2% J - 5%	Contact factory for additional options	99 - 0.040" BeO		Blank - Bulk TR - Tape and Reel WP - Waffle Pack	

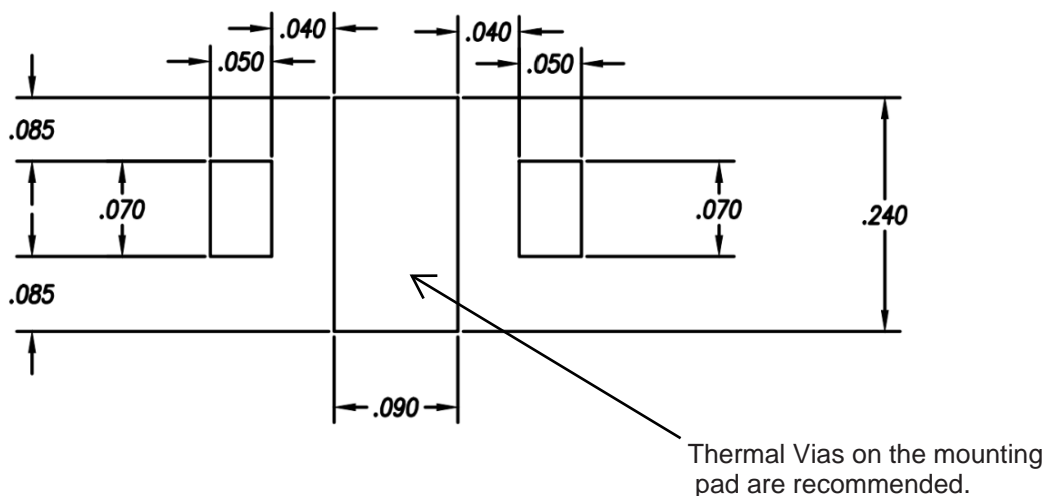
Terminal Metallization

AS -	Tin Lead over Platinum Palladium Gold
CB -	Tin Lead over Nickel over Silver
CC -	100% Matte Tin over Copper over Silver
CT -	100% Matte Tin over Nickel over Silver
HA -	Gold over Platinum Gold I/O Terminals w/ Platinum Palladium Gold Backplane
JA -	Gold over Platinum Palladium Gold

RoHS	Magnetic	Solder	Epoxy	Wirebond
No	No	Yes	No	No
No	Yes	Yes	No	No
Yes	No	Yes	No	No
Yes	Yes	Yes	No	No
Yes	No	Yes (Backplane)	Yes	Yes (I/O Terminals)
Yes	No	No	Yes	Yes

Barry Industries reserves the right to change part number and/or process without notification.

RYC2525ZZ-XXXXWN-99 Recommended Footprint:



RYC2525ZZ-XXXXWN-99 Reliability Specifications:

Parameter:	Test Condition:	Results:
Short Time Overload	Apply 1.1x Rated Power for 5 Seconds.	≤ 5.0% Resistance Shift
Rated Load Life	Apply 1/2 Power Under 40°C ±2°C 90 Minutes on/ 30 Minutes off. Repeat for 100 hours	≤ 5.0% Resistance Shift
Moisture Resistance	MIL-PRF-55342 para 4.8.9 95% RH, 25°C - 65°C	≤ 5.0% Resistance Shift
Resistance to Soldering Heat	MIL-STD-202 Method 210 and MIL-PRF-55342 Para 4.8.8.1	≤ 5.0% Resistance Shift
Resistance to Wire-Bonding Exposure	MIL-PRF-55342 Para 4.8.8.2	≤ 5.0% Resistance Shift
Solderability	MIL-PRF-55342 Para 4.8.12	>95% Covered
High Temperature Storage	125°C ±2°C for 500 Hours	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)
Thermal Shock	-65°C to +150°C 30 Minutes Dwell, 5 Cycles	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)

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